



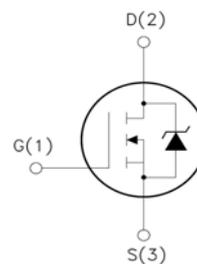
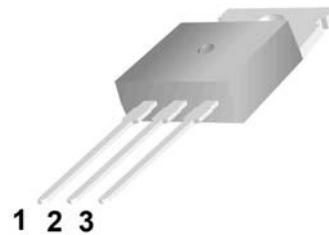
奥德利®  
AUDLEY

FP7N60

Features:

- Low Intrinsic Capacitances.
- Excellent Switching Characteristics.
- Extended Safe Operating Area.
- Unrivalled Gate Charge :Qg=29nC (Typ.).
- BVDSS=600V, I<sub>D</sub>=7A
- R<sub>DS(on)</sub> : 1.2Ω (Max) @V<sub>G</sub>=10V
- 100% Avalanche Tested

TO-220



- 1.Gate (G)
- 2.Drain (D)
- 3.Source (S)

**Absolute Maximum Ratings** (T<sub>a</sub>=25°C Unless otherwise noted)

Symbol	Parameter	Value	Unit
V <sub>DSS</sub>	Drain-Source Voltage	600	V
I <sub>D</sub>	Drain Current	T <sub>C</sub> =25°C	7
		T <sub>C</sub> =100°C	4.7
V <sub>GS(TH)</sub>	Gate Threshold Voltage	±30	V
E <sub>AS</sub>	Single Pulse Avalanche Energy (note1)	420	mJ
I <sub>AR</sub>	Avalanche Current (note2)	7	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	147	W
T <sub>j</sub>	Junction Temperature(Max)	150	°C
T <sub>stg</sub>	Storage Temperature	-55~+150	°C
TL	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	°C

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJC</sub>	Thermal Resistance, Junction to Case	-	0.88	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient	-	62.5	°C/W
R <sub>θCS</sub>	Thermal Resistance, Case to Sink	0.5	-	°C/W

**Electrical Characteristics** (Ta=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0	600	-	-	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> =250μA, Reference to 25°C	-	0.67	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =600V, V <sub>GS</sub> =0V	-	-	10	μA
		V <sub>DS</sub> =480V, T <sub>c</sub> =125°C	-	-	100	
I <sub>GSSF</sub>	Gate-body leakage Current, Forward	V <sub>GS</sub> =+30V, V <sub>DS</sub> =0V	-	-	100	nA
I <sub>GSSR</sub>	Gate-body leakage Current, Reverse	V <sub>GS</sub> =-30V, V <sub>DS</sub> =0V	-	-	-100	
<b>On Characteristics</b>						
V <sub>GS(TH)</sub>	Gate Threshold Voltage	I <sub>D</sub> =250μA, V <sub>DS</sub> =V <sub>GS</sub>	2	-	4	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	I <sub>D</sub> =3.5A, V <sub>GS</sub> =10V	-	-	1.2	Ω
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0, f=1.0MHz	-	1100	1430	pF
C <sub>oss</sub>	Output Capacitance		-	135	175	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	16	21	
<b>Switching Characteristics</b>						
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =300V, I <sub>D</sub> =7A R <sub>G</sub> =25Ω (Note 3,4)	-	30	70	ns
T <sub>r</sub>	Turn-On Rise Time		-	80	170	
T <sub>d(off)</sub>	Turn-Off Delay Time		-	65	140	
T <sub>f</sub>	Turn-Off Rise Time		-	60	140	
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =480V, V <sub>GS</sub> =10V, I <sub>D</sub> =7A (Note 3,4)	-	29	38	nC
Q <sub>gs</sub>	Gate-Source Charge		-	7	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	14.5	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Max. Diode Forward Current	-	-	-	7	A
I <sub>SM</sub>	Max. Pulsed Forward Current	-	-	-	28	
V <sub>SD</sub>	Diode Forward Voltage	I <sub>D</sub> =7A	-	-	1.5	V
T <sub>rr</sub>	Reverse Recovery Time	I <sub>S</sub> =7A, V <sub>GS</sub> =0V diF/dt=100A/μs (Note3)	-	320	-	μs
Q <sub>rr</sub>	Reverse Recovery Charge		-	2.4	-	μC

- Notes : 1, L=6mH, I<sub>AS</sub>=7A, V<sub>DD</sub>=50V, R<sub>G</sub>=25Ω, Starting T<sub>J</sub> =25°C  
 2, Repetitive Rating : Pulse width limited by maximum junction temperature  
 3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%  
 4, Essentially Independent of Operating Temperature

Typical Characteristics

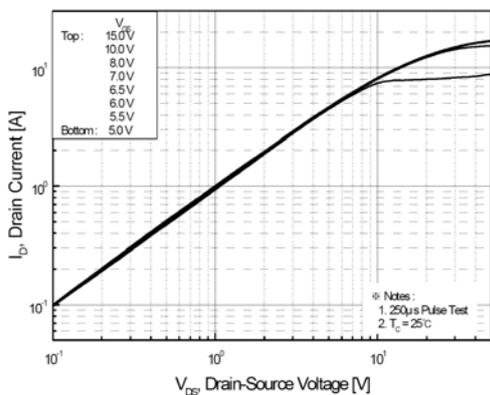


Figure 1. On-Region Characteristics

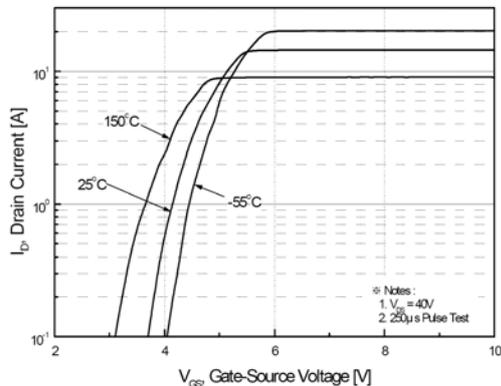


Figure 2. Transfer Characteristics

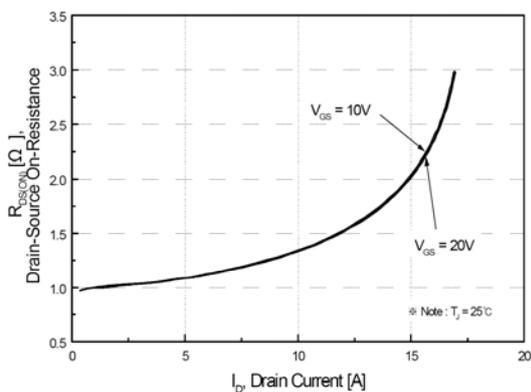


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

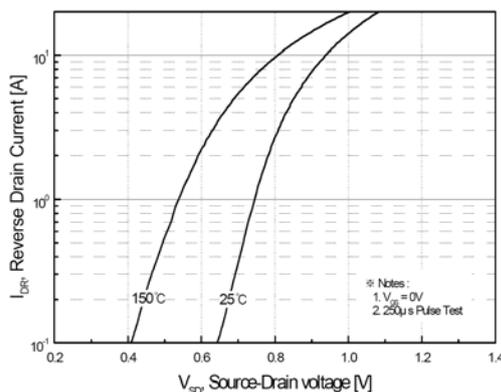


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

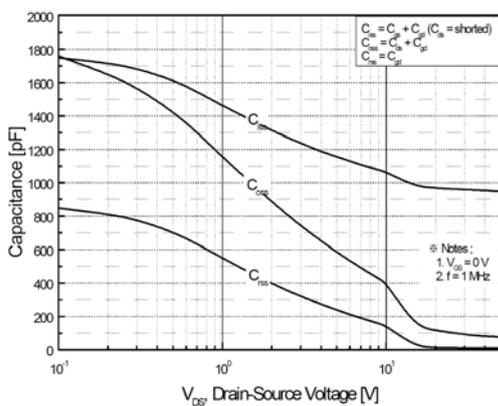


Figure 5. Capacitance Characteristics

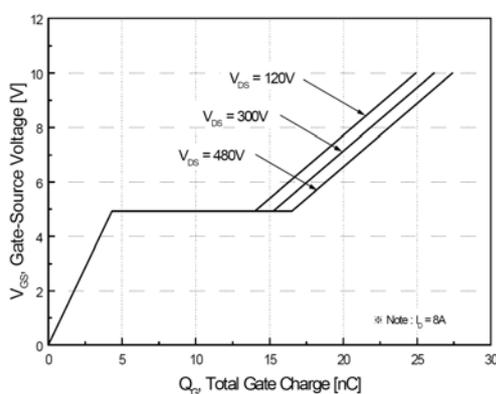


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

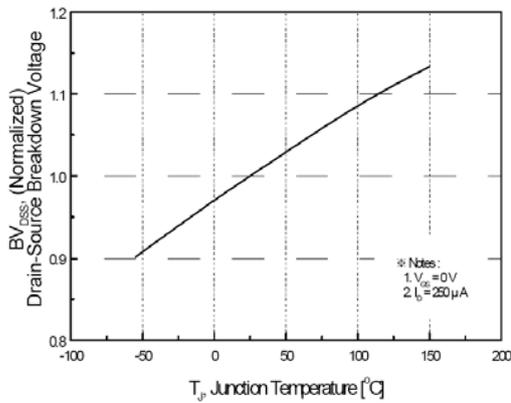


Figure 7. Breakdown Voltage Variation vs Temperature

Package Dimension

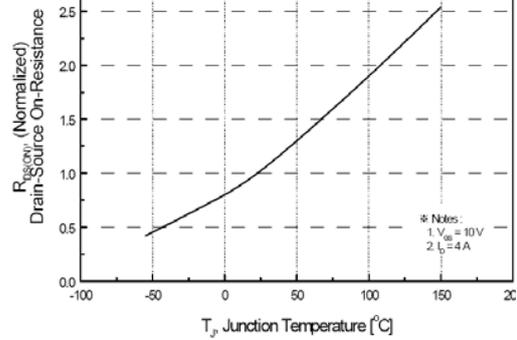


Figure 8. On-Resistance Variation vs Temperature

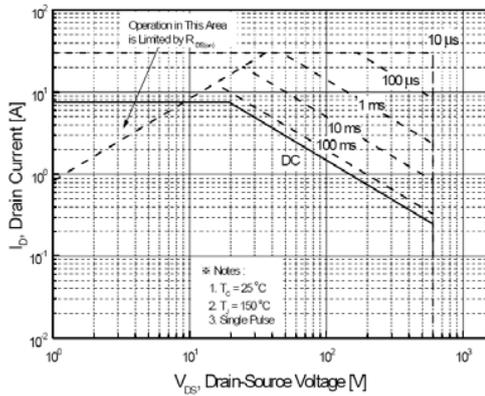


Figure 9-1. Maximum Safe Operating Area for WGP7N60

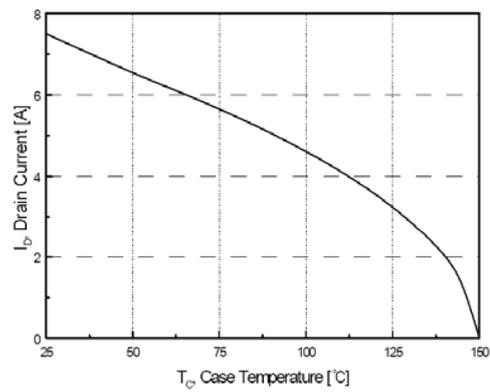


Figure 10. Maximum Drain Current vs Case Temperature

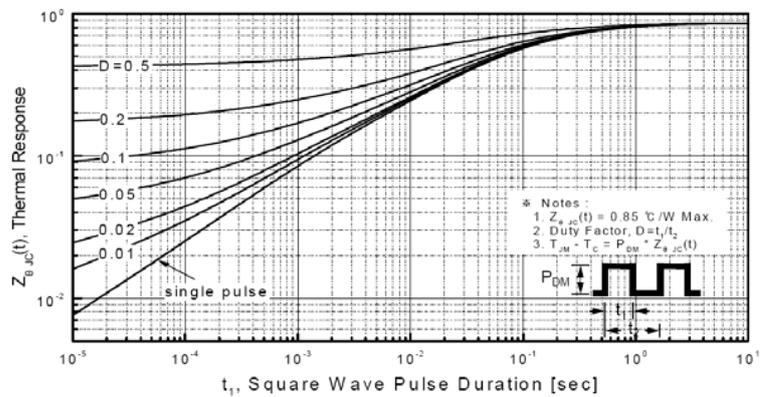


Figure 11-1. Transient Thermal Response Curve for WGP7N60

# FP7N60

600V N-Channel MOSFET

Unit: mm

